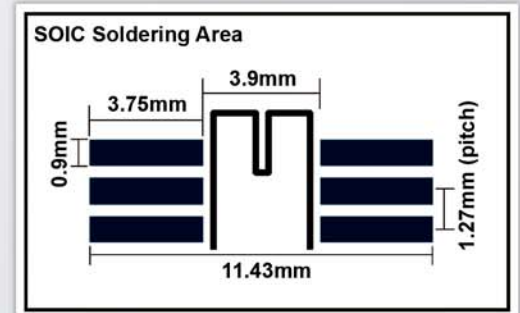
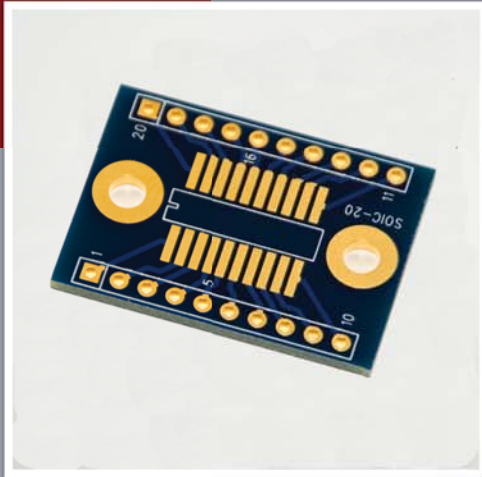


SOIC Prototyping board

PT-SOIC



SOIC Pad:
accepts narrow or wide body packages with 1.27mm pitch

Hole Diameter:
0.047" (1.2mm) plated holes

Hole Spacing:
0.1" (2.54mm)

T/H Pad:
0.08" (2.032mm) round pad

Type/Finish:
FR-4 with Electroless Nickel Immersion Gold (ENIG)

PCB Thickness:
0.062" (1.57mm)

Mounting Holes:
4-40 size, plated

The SOIC prototyping boards are designed to allow quick and easy circuit prototyping of chips using the SOIC Package. The SOIC soldering area was designed to accommodate both narrow body (SOIC-N) and wide body (SOIC-W) package types. The boards also offer 0.08" round pads with 0.047" plated holes spaced 0.1" apart which can be used to solder DIP headers or wires to interface with the SOIC chip. The spacing of the holes also allows the boards to be connected to a standard 0.1" pitch bread-board with ease.

Ordering Information

Part Number	No. of Pads	Board Dimensions
PT-SOIC-8	8	0.85" x 0.82"
PT-SOIC-14	14	1.00" x 0.82"
PT-SOIC-16	16	1.00" x 0.82"
PT-SOIC-18	18	1.15" x 0.82"
PT-SOIC-20	20	1.15" x 0.82"
PT-SOIC-24	24	1.30" x 0.82"
PT-SOIC-28	28	1.45" x 0.82"
PT-SOIC-32	32	1.70" x 0.82"
PT-SOIC-36	36	1.85" x 0.82"
PT-SOIC-44	44	2.45" x 0.82"
PT-SOIC-48	48	2.45" x 0.82"
PT-SOIC-54	54	2.80" x 0.82"